

## Operation: SMT+DIP 3.1 Type-C 连接器 / 24PIN 卧式



**LTEM NO.: MC-312D-C**  
(L7.90mm × W8.94mm × H3.20mm CONNECTORS)



### Technical parameter

PROJECT	LEVEL	A[better product]	B[average product]
	Contact Rating	5.0A, 12V DC	
Electrical Properties	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	10,000 Cycles	8,000 Cycles
	Rated Load	8,500 Cycles	6,500 Cycles
	Storage temp.	-35℃~+75℃(Operating Temp: )	

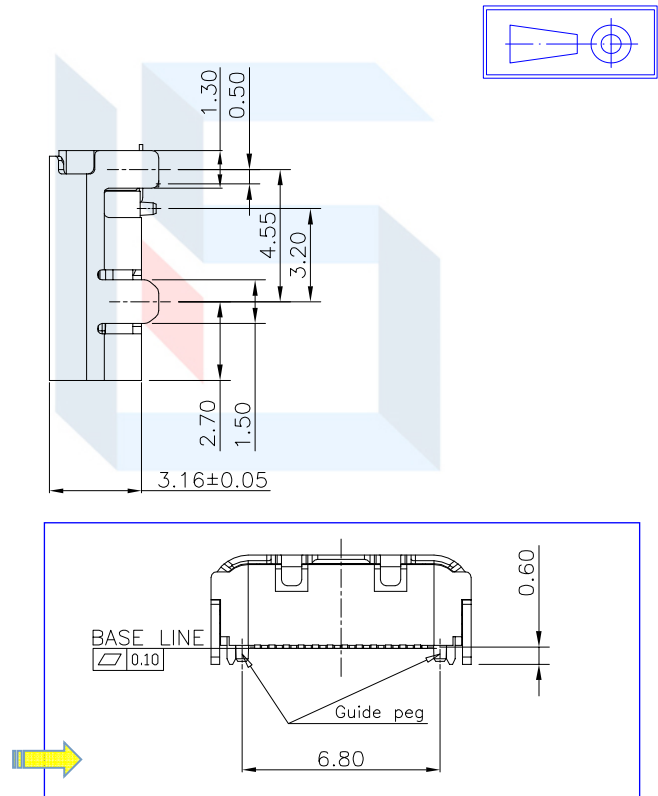
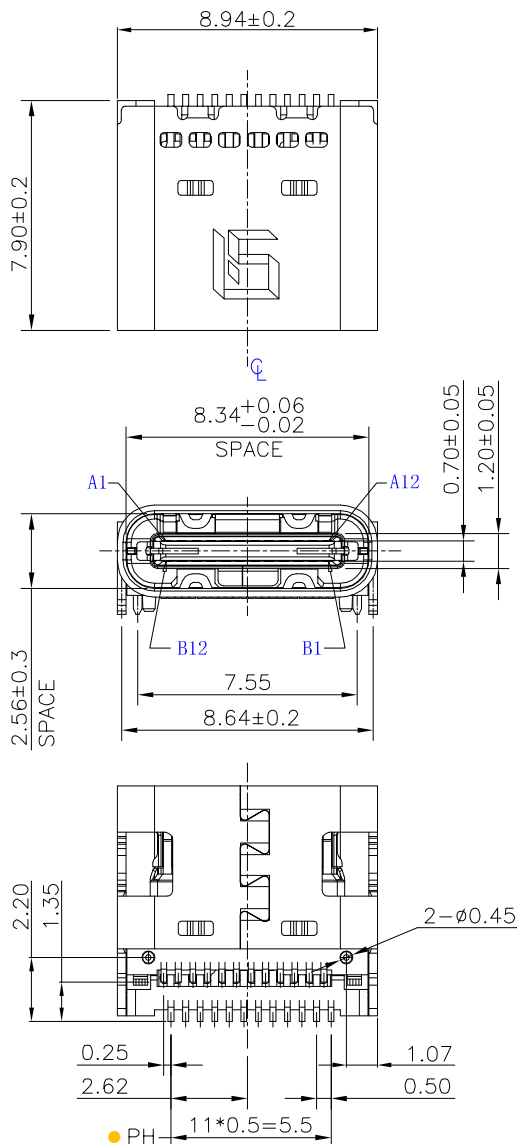
表面 SMT+DIP

側向導入 LATERAL  
精密部品 NICETY

可靠 STABILIZE

適合環保 RoHS

Unit:mm



Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μ m Ni PLATED OVERALL; 0.25 μ m Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
② B	HOUSING 基座	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
③ C	SHIELDING PLATE 屏蔽壳	STAINLESS STEE	【G/F】 0.25 μ m Ni PLATED OVERALL;
④ D	SHELL 外壳	STAINLESS STEE	【G/F】 0.25 μ m Ni PLATED OVERALL;
⑤ E	GND RING 接地件	STAINLESS STEE	STAINLESS STEEL;

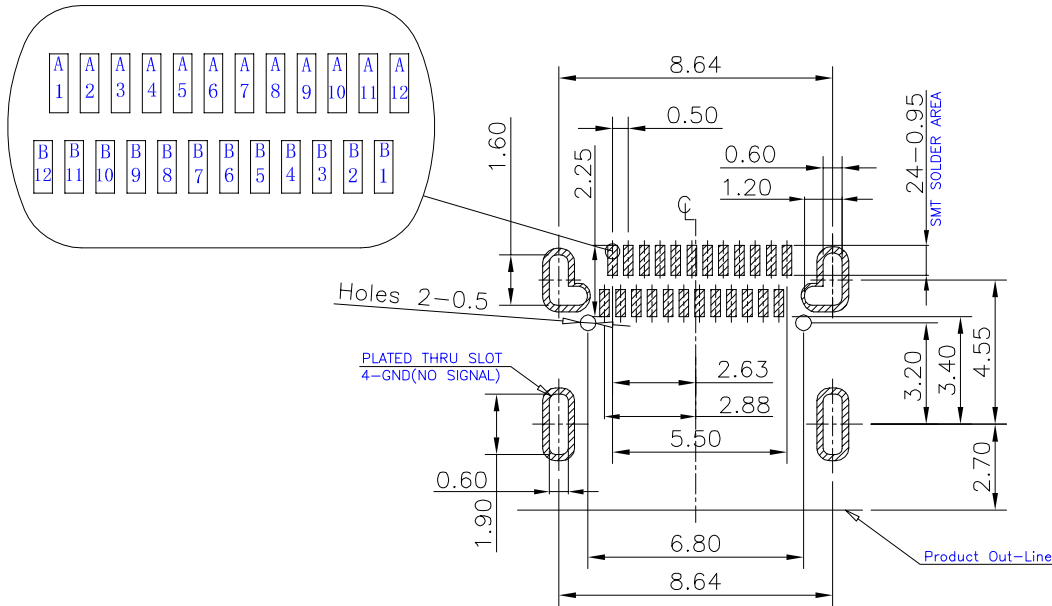
Operating Force

Inward  
Exiting

5.0~8.0N. (1N.=100gram-force)  
5.0~8.0N. (1N.=100gram-force)

Solder-ability (Max.)

IR Reflow: 255°C, 5sec. Manual: 350°C, 3sec.

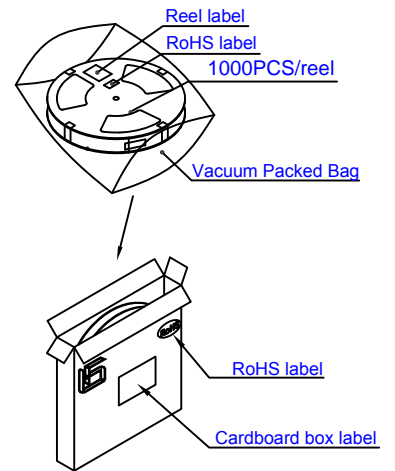


DECIMALS	ANGLES
.X :±0.25	X.° :±1.5°
.XX :±0.15	XX.° :±1.0°
.XXX :±0.10	.XXX° :±0.5°

Pin Definition



PIN	Signal NAME	Description	PIN	Signal NAME	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A4	V BUS	Bus Power	B9	V BUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use (SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use (SBU)	B5	CC2	Configuration Channel
A9	V BUS	Bus Power	B4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B1	GND	Ground return



本品不屬於危害性廢棄物,須丟棄時可以委託回收商予以回收再生處理。  
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